

SUBSTRATE PROCESSING METHOD

ABSTRACT

Provided is a method for processing a substrate having a metal formed on a planned dividing line along the planned dividing line, the method including a processed groove forming step of forming a processed groove in the substrate along the planned dividing line, and a burr removing step of, after the processed groove forming step is performed, making an etchant that includes at least an oxidizing agent and to which an ultrasonic vibration is imparted come into contact with the substrate, suppressing ductility of a metallic burr generated on a periphery of the formed processed groove and increasing fragility of the burr by modifying the burr by the oxidizing agent included in the etchant, and removing the burr by the ultrasonic vibration.

[Fig. 4]